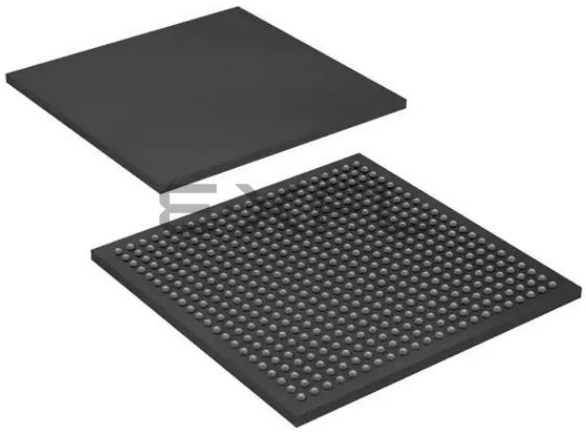

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Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	4713
Number of Logic Elements/Cells	75408
Total RAM Bits	2810880
Number of I/O	292
Number of Gates	-
Voltage - Supply	1.15V ~ 1.25V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	484-BGA
Supplier Device Package	484-FBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep4ce75f23c8n

Power-Up Conditions and Memory Initialization

The M9K memory block outputs of Cyclone IV devices power up to zero (cleared) regardless of whether the output registers are used or bypassed. All M9K memory blocks support initialization using a **.mif**. You can create **.mif**s in the Quartus II software and specify their use using the RAM MegaWizard Plug-In Manager when instantiating memory in your design. Even if memory is pre-initialized (for example, using a **.mif**), it still powers up with its outputs cleared. Only the subsequent read after power up outputs the pre-initialized values.

For more information about **.mif**s, refer to the *RAM Megafunction User Guide* and the *Quartus II Handbook*.

Power Management

The M9K memory block clock enables of Cyclone IV devices allow you to control clocking of each M9K memory block to reduce AC power consumption. Use the `rden` signal to ensure that read operations only occur when necessary. If your design does not require read-during-write, reduce power consumption by deasserting the `rden` signal during write operations or any period when there are no memory operations. The Quartus II software automatically powers down any unused M9K memory blocks to save static power.

Document Revision History

Table 3–6 shows the revision history for this chapter.

Table 3–6. Document Revision History

Date	Version	Changes
November 2011	1.1	Updated the “Byte Enable Support” section.
November 2009	1.0	Initial release.

5. Clock Networks and PLLs in Cyclone IV Devices

CYIV-51005-2.4

This chapter describes the hierarchical clock networks and phase-locked loops (PLLs) with advanced features in the Cyclone® IV device family. It includes details about the ability to reconfigure the PLL counter clock frequency and phase shift in real time, allowing you to sweep PLL output frequencies and dynamically adjust the output clock phase shift.

☞ The Quartus® II software enables the PLLs and their features without external devices.

This chapter contains the following sections:

Clock Networks

The Cyclone IV GX device provides up to 12 dedicated clock pins (`CLK[15..4]`) that can drive the global clocks (GCLKs). Cyclone IV GX devices support four dedicated clock pins on each side of the device except the left side. These clock pins can drive up to 30 GCLKs.

The Cyclone IV E device provides up to 15 dedicated clock pins (`CLK[15..1]`) that can drive up to 20 GCLKs. Cyclone IV E devices support three dedicated clock pins on the left side and four dedicated clock pins on the top, right, and bottom sides of the device except EP4CE6 and EP4CE10 devices. EP4CE6 and EP4CE10 devices only support three dedicated clock pins on the left side and four dedicated clock pins on the right side of the device.

Table 6–2 on page 6–7 shows the possible settings for I/O standards with current strength control. These programmable current strength settings are a valuable tool in helping decrease the effects of simultaneously switching outputs (SSO) in conjunction with reducing system noise. The supported settings ensure that the device driver meets the specifications for IOH and IOL of the corresponding I/O standard.

☞ When you use programmable current strength, on-chip series termination (R_S OCT) is not available.

Slew Rate Control

The output buffer for each Cyclone IV I/O pin provides optional programmable output slew-rate control. Table 6–2 on page 6–7 shows the possible slew rate option and the Quartus II default slew rate setting. However, these fast transitions may introduce noise transients in the system. A slower slew rate reduces system noise, but adds a nominal delay to rising and falling edges. Because each I/O pin has an individual slew-rate control, you can specify the slew rate on a pin-by-pin basis. The slew-rate control affects both the rising and falling edges. Slew rate control is available for single-ended I/O standards with current strength of 8 mA or higher.

☞ You cannot use the programmable slew rate feature when using OCT with calibration.

☞ You cannot use the programmable slew rate feature when using the 3.0-V PCI, 3.0-V PCI-X, 3.3-V LVTTL, or 3.3-V LVCMOS I/O standards. Only the fast slew rate (default) setting is available.

Open-Drain Output

Cyclone IV devices provide an optional open-drain (equivalent to an open-collector) output for each I/O pin. This open-drain output enables the device to provide system-level control signals (for example, interrupt and write enable signals) that are asserted by multiple devices in your system.

Bus Hold

Each Cyclone IV device user I/O pin provides an optional bus-hold feature. The bus-hold circuitry holds the signal on an I/O pin at its last-driven state. Because the bus-hold feature holds the last-driven state of the pin until the next input signal is present, an external pull-up or pull-down resistor is not necessary to hold a signal level when the bus is tri-stated.

The bus-hold circuitry also pulls undriven pins away from the input threshold voltage in which noise can cause unintended high-frequency switching. You can select this feature individually for each I/O pin. The bus-hold output drives no higher than V_{CCIO} to prevent overdriving signals.

☞ If you enable the bus-hold feature, the device cannot use the programmable pull-up option. Disable the bus-hold feature when the I/O pin is configured for differential signals. Bus-hold circuitry is not available on dedicated clock pins.

Bus-hold circuitry is only active after configuration. When going into user mode, the bus-hold circuit captures the value on the pin present at the end of configuration.

Table 6–2. Cyclone IV Device I/O Features Support (Part 2 of 2)

I/O Standard	IOH/IOL Current Strength Setting (mA) (1), (9)		R_S OCT with Calibration Setting, Ohm (Ω)		R_S OCT Without Calibration Setting, Ohm (Ω)		Cyclone IV E I/O Banks Support	Cyclone IV GX I/O Banks Support	Slew Rate Option (6)	PCI-clamp Diode Support
	Column I/O	Row I/O	Column I/O	Row I/O (8)	Column I/O	Row I/O (8)				
BLVDS	8,12,16	8,12,16	—	—	—	—	1,2,3,4, 5,6,7,8	3,4,5,6, 7,8	0,1,**2**	—
LVDS (3)	—	—	—	—	—	—		5,6	—	—
PPDS (3), (4)	—	—	—	—	—	—			—	—
RSDS and mini-LVDS (3), (4)	—	—	—	—	—	—			—	—
Differential LVPECL (5)	—	—	—	—	—	—		3,4,5,6, 7,8	—	—

Notes to Table 6–2:

(1) The default current strength setting in the Quartus II software is 50-Ω OCT without calibration for all non-voltage reference and HSTL/SSTL Class I I/O standards. The default setting is 25-Ω OCT without calibration for HSTL/SSTL Class II I/O standards.

(2) The differential SSTL-18 and SSTL-2, differential HSTL-18, HSTL-15, and HSTL-12 I/O standards are supported only on clock input pins and PLL output clock pins.

(3) True differential (PPDS, LVDS, mini-LVDS, and RSDS I/O standards) outputs are supported in row I/O banks 1, 2, 5, and 6 only for Cyclone IV E devices and right I/O banks 5 and 6 only for Cyclone IV GX devices. Differential outputs in column I/O banks require an external resistor network.

(4) This I/O standard is supported for outputs only.

(5) This I/O standard is supported for clock inputs only

(6) The default Quartus II slew rate setting is in bold; **2** for all I/O standards that supports slew rate option.

(7) Differential SSTL-18, differential HSTL-18, HSTL-15, and HSTL-12 I/O standards do not support Class II output.

(8) Cyclone IV GX devices only support right I/O pins.

(9) Altera not only offers current strength that meets the industrial standard specification but also other additional current strengths.

☞ For more details about the differential I/O standards supported in Cyclone IV I/O banks, refer to "High-Speed I/O Interface" on page 6–24.

On-Chip Series Termination with Calibration

Cyclone IV devices support R_S OCT with calibration in the top, bottom, and right I/O banks. The R_S OCT calibration circuit compares the total impedance of the I/O buffer to the external 25-Ω ±1% or 50-Ω ±1% resistors connected to the RUP and RDN pins, and dynamically adjusts the I/O buffer impedance until they match (as shown in Figure 6–2).

Voltage-Referenced I/O Standard Termination

Voltage-referenced I/O standards require an input reference voltage (V_{REF}) and a termination voltage (V_{TT}). The reference voltage of the receiving device tracks the termination voltage of the transmitting device, as shown in Figure 6–5 and Figure 6–6.

Figure 6–5. Cyclone IV Devices HSTL I/O Standard Termination

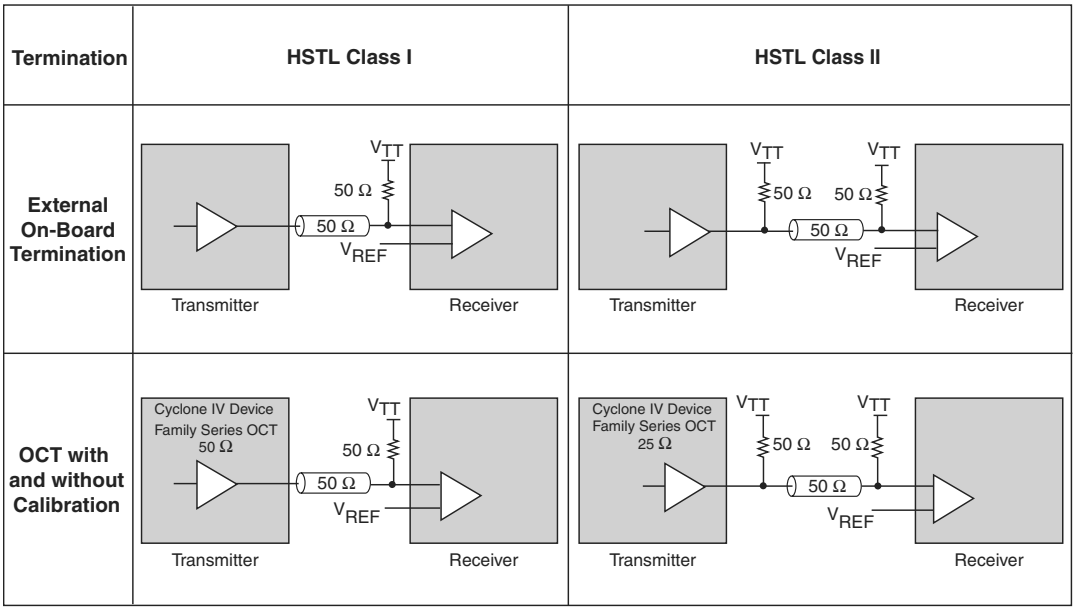


Figure 6–6. Cyclone IV Devices SSTL I/O Standard Termination

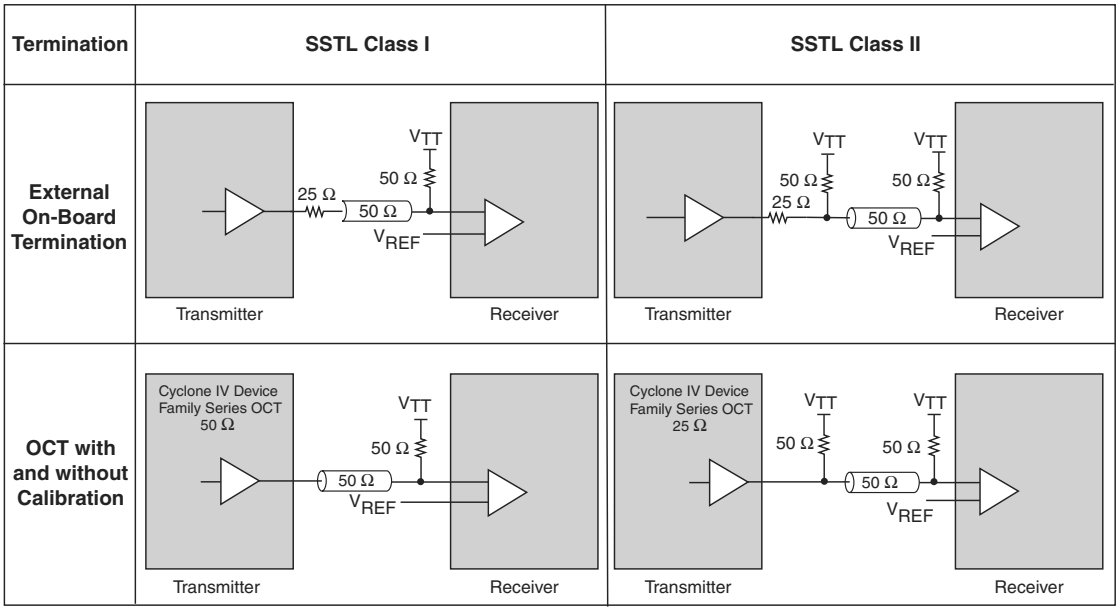


Table 6–9. Cyclone IV GX I/O, Differential, and XCVRs Channel Count

Device	4CGX15	4CGX22		4CGX30			4CGX50		4CGX75		4CGX110			4CGX150		
Numbers of Differential Channels (1), (2)	169-FBGA	169-FBGA	324-FBGA	169-FBGA	324-FBGA	484-FBGA	484-FBGA	672-FBGA	484-FBGA	672-FBGA	484-FBGA	672-FBGA	896-FBGA	484-FBGA	672-FBGA	896-FBGA
User I/O (3)	72	72	150	72	150	290	290	310	290	310	270	393	475	270	393	475
User I/O banks	9 (4)	9 (4)	9 (4)	9 (4)	9 (4)	11 (5)	11 (5), (6)	11 (5), (6)	11 (5), (6)	11 (5), (6)	11 (5), (6)	11 (5), (6)	11 (5), (6)	11 (5), (6)	11 (5), (6)	11 (5), (6)
LVDS (7), (9)	9	9	16	9	16	45	45	51	45	51	38	52	63	38	52	63
Emulated LVDS (8), (9)	16	16	48	16	48	85	85	89	85	89	82	129	157	82	129	157
XCVRs	2	2	4	2	4	4	4	8	4	8	4	8	8	4	8	8

Notes to Table 6–9:

(1) User I/O pins are used as inputs or outputs; clock input pins are used as inputs only; clock output pins are used as outputs only.

(2) For differential pad placement guidelines, refer to "Pad Placement" on page 6–23.

(3) The I/O pin count includes all GPIOs, dedicated clock pins, and dual-purpose configuration pins. Transceivers pins and dedicated configuration pins are not included in the pin count.

(4) Includes one configuration I/O bank and two dedicated clock input I/O banks for HSSI input reference clock.

(5) Includes one configuration I/O bank and four dedicated clock input I/O banks for HSSI input reference clock.

(6) Single-ended clock input support is available for dedicated clock input I/O banks 3B (pins CLKIO20 and CLKIO22) and 8B (pins CLKIO17 and CLKIO19).

(7) The true LVDS count includes all LVDS I/O pairs, differential clock input and clock output pins in right I/O banks 5 and 6.

(8) The emulated LVDS count includes all LVDS I/O pairs, differential clock input and clock output pins in column I/O banks 3, 4, 7, and 8.

(9) LVDS input and output buffers are sharing the same p and n pins. One LVDS I/O channel can only be either transmitter or receiver at a time.

High-Speed I/O Standards Support

This section provides information about the high-speed I/O standards and the HSSI input reference clock supported in Cyclone IV devices.

High Speed Serial Interface (HSSI) Input Reference Clock Support

Cyclone IV GX devices support the same I/O features for GPIOs with additional new features where current I/O banks 3A and 8A consist of dual-purpose clock input pins (CLKIN) and 3B and 8B consist of dedicated CLKIN that can be used to support the high-speed transceiver input reference clock (REFCLK) features on top of the general-purpose clock input function.

The EP4CGX15, EP4CGX22, and EP4CGX30 devices contain two pairs of CLKIN/REFCLK pins located in I/O banks 3A and 8A. I/O banks 3B and 8B are not available in EP4CGX15, EP4CGX22, and EP4CGX30 devices. The EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150 devices have a total of four pairs of CLKIN/REFCLK pins located in I/O banks 3A, 3B, 8A, and 8B. I/O banks 3B and 8B can also support single-ended clock inputs. For more information about the CLKIN/REFCLK pin location, refer to Figure 6–10 on page 6–18 and Figure 6–11 on page 6–19.

The first Cyclone IV device in the chain is the configuration master and it controls the configuration of the entire chain. Other Altera devices that support PS configuration can also be part of the chain as configuration slaves.

☞ In the multi-device AS configuration, the board trace length between the serial configuration device and the master device of the Cyclone IV device must follow the recommendations in Table 8–7 on page 8–18.

The nSTATUS and CONF_DONE pins on all target devices are connected together with external pull-up resistors, as shown in Figure 8–3 on page 8–13. These pins are open-drain bidirectional pins on the devices. When the first device asserts nCEO (after receiving all its configuration data), it releases its CONF_DONE pin. However, the subsequent devices in the chain keep this shared CONF_DONE line low until they receive their configuration data. When all target devices in the chain receive their configuration data and release CONF_DONE, the pull-up resistor drives a high level on CONF_DONE line and all devices simultaneously enter initialization mode.

☞ Although you can cascade Cyclone IV devices, serial configuration devices cannot be cascaded or chained together.

If the configuration bitstream size exceeds the capacity of a serial configuration device, you must select a larger configuration device, enable the compression feature, or both. When configuring multiple devices, the size of the bitstream is the sum of the individual device's configuration bitstream.

Configuring Multiple Cyclone IV Devices with the Same Design

Certain designs require that you configure multiple Cyclone IV devices with the same design through a configuration bitstream, or a **.sof**. You can do this through the following methods:

- Multiple **.sof**
- Single **.sof**

☞ For both methods, the serial configuration devices cannot be cascaded or chained together.

Multiple SRAM Object Files

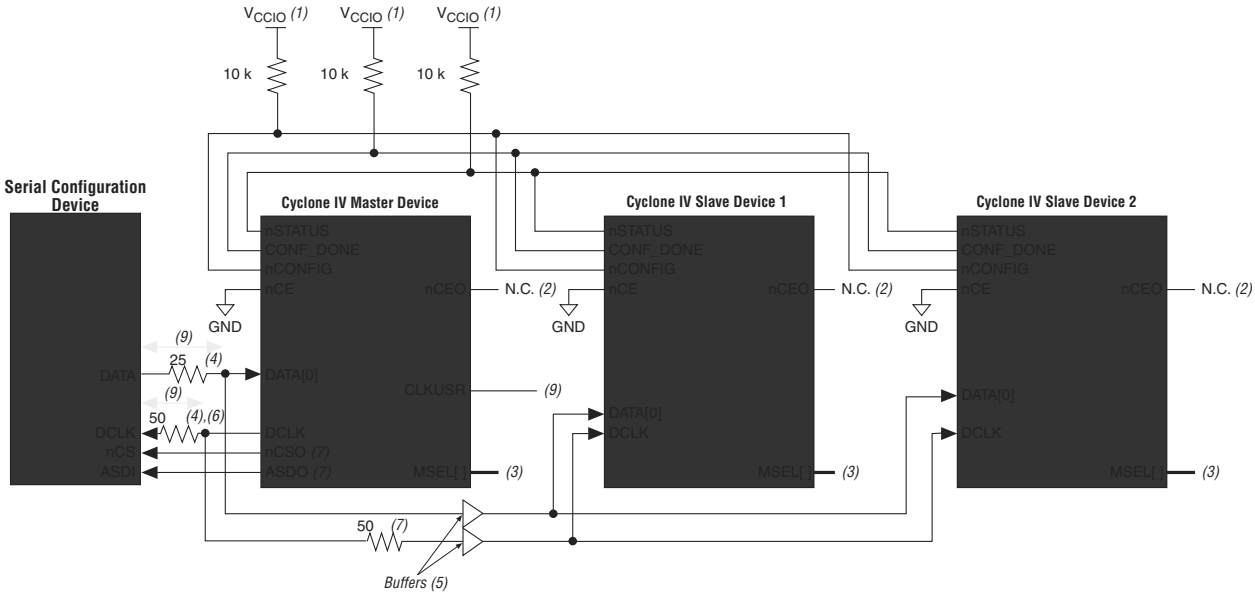
Two copies of the **.sof** are stored in the serial configuration device. Use the first copy to configure the master device of the Cyclone IV device and the second copy to configure all remaining slave devices concurrently. All slave devices must have the same density and package. The setup is similar to Figure 8–3 on page 8–13.

To configure four identical Cyclone IV devices with the same **.sof**, you must set up the chain similar to the example shown in Figure 8–4. The first device is the master device and its MSEL pins must be set to select AS configuration. The other three slave devices are set up for concurrent configuration and their MSEL pins must be set to select PS configuration. The nCEO pin from the master device drives the nCE input pins on all three slave devices, as well as the DATA and DCLK pins that connect in parallel to all

Single SRAM Object File

The second method configures both the master device and slave devices with the same **.sof**. The serial configuration device stores one copy of the **.sof**. You must set up one or more slave devices in the chain. All the slave devices must be set up in the same way (Figure 8–5).

Figure 8–5. Multi-Device AS Configuration in Which Devices Receive the Same Data with a Single .sof



Notes to Figure 8–5:

(1) Connect the pull-up resistors to the V_{CCIO} supply of the bank in which the pin resides.

(2) The nCEO pin is left unconnected or used as a user I/O pin when it does not feed the nCE pin of another device.

(3) The MSEL pin settings vary for different configuration voltage standards and POR time. You must set the master device of the Cyclone IV device in AS mode and the slave devices in PS mode. To connect the MSEL pins for the master device in AS mode and slave devices in PS mode, refer to Table 8–3 on page 8–8, Table 8–4 on page 8–8, and Table 8–5 on page 8–9. Connect the MSEL pins directly to V_{CCA} or GND.

(4) Connect the series resistor at the near end of the serial configuration device.

(5) Connect the repeater buffers between the master and slave devices for DATA[0] and DCLK. All I/O inputs must maintain a maximum AC voltage of 4.1 V. The output resistance of the repeater buffers must fit the maximum overshoot equation outlined in "Configuration and JTAG Pin I/O Requirements" on page 8–5.

(6) The 50-Ω series resistors are optional if the 3.3-V configuration voltage standard is applied. For optimal signal integrity, connect these 50-Ω series resistors if the 2.5- or 3.0-V configuration voltage standard is applied.

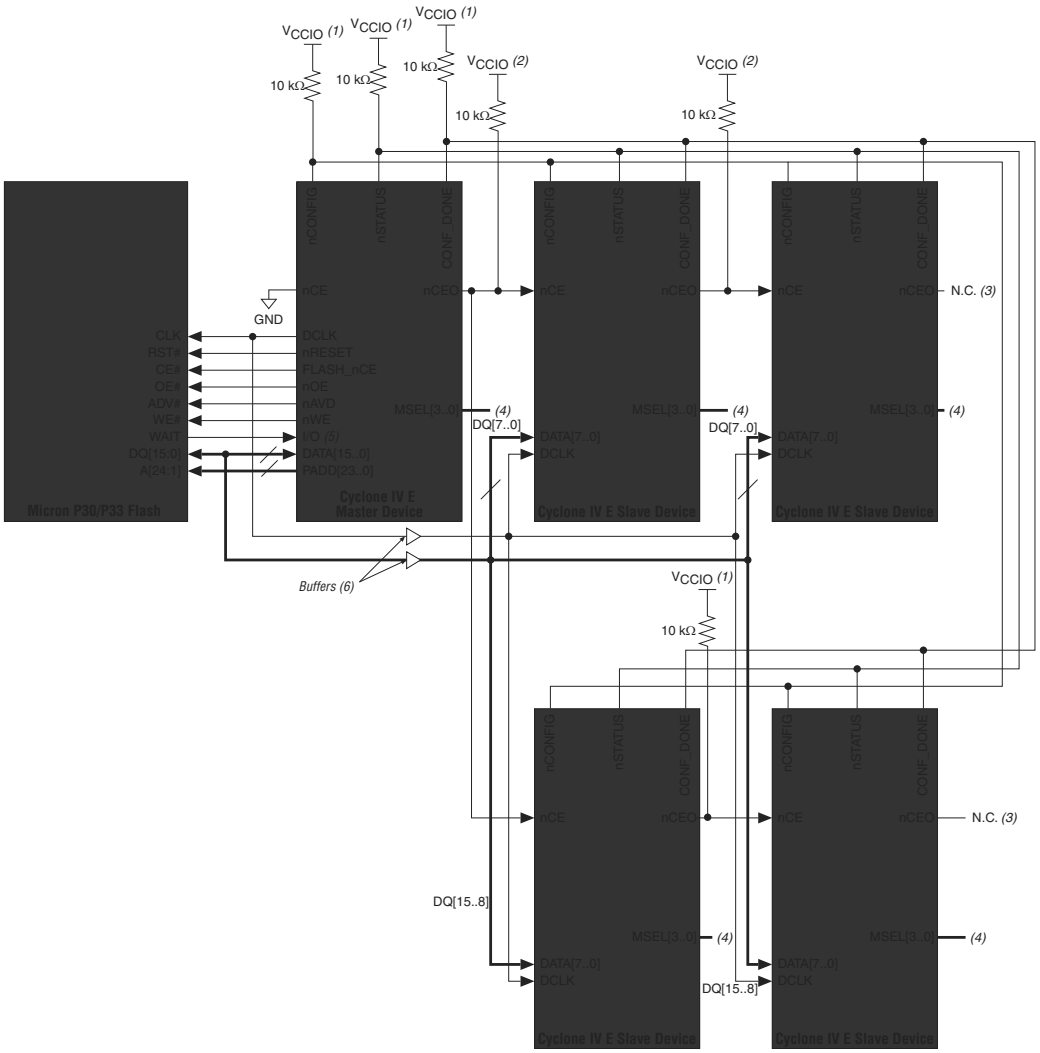
(7) These pins are dual-purpose I/O pins. The nCSO pin functions as FLASH_nCE pin in AP mode. The ASDO pin functions as DATA[1] pin in AP and FPP modes.

(8) Only Cyclone IV GX devices have an option to select CLKUSR (40 MHz maximum) as the external clock source for DCLK.

(9) For multi-devices AS configuration using Cyclone IV E with 1,0 V core voltage, the maximum board trace-length from the serial configuration device to the junction-split on both DCLK and Data0 line is 3.5 inches.

In this setup, all the Cyclone IV devices in the chain are connected for concurrent configuration. This reduces the AS configuration time because all the Cyclone IV devices are configured in one configuration cycle. Connect the nCE input pins of all the Cyclone IV devices to GND. You can either leave the nCEO output pins on all the Cyclone IV devices unconnected or use the nCEO output pins as normal user I/O pins. The DATA and DCLK pins are connected in parallel to all the Cyclone IV devices.

Figure 8–9. Word-Wide Multi-Device AP Configuration



Notes to Figure 8–9:

(1) Connect the pull-up resistors to the V_{CCIO} supply of the bank in which the pin resides.

(2) Connect the pull-up resistor to the V_{CCIO} supply voltage of the I/O bank in which the `nCE` pin resides.

(3) The `nCEO` pin is left unconnected or used as a user I/O pin when it does not feed the `nCE` pin of another device.

(4) The `MSEL` pin settings vary for different configuration voltage standards and POR time. You must set the master device in AP mode and the slave devices in FPP mode. To connect `MSEL[3..0]` for the master device in AP mode and the slave devices in FPP mode, refer to Table 8–5 on page 8–9. Connect the `MSEL` pins directly to V_{CCA} or GND.

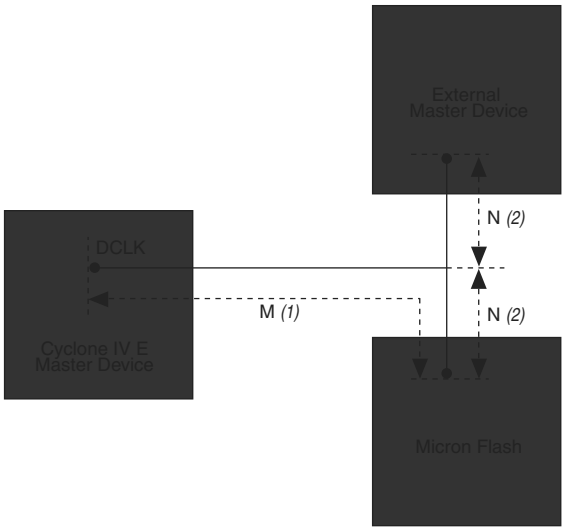
(5) The AP configuration ignores the `WAIT` signal during configuration mode. However, if you are accessing flash during user mode with user logic, you can optionally use the normal I/O pin to monitor the `WAIT` signal from the Micron P30 or P33 flash.

(6) Connect the repeater buffers between the Cyclone IV E master device and slave devices for `DATA[15..0]` and `DCLK`. All I/O inputs must maintain a maximum AC voltage of 4.1 V. The output resistance of the repeater buffers must fit the maximum overshoot equation outlined in "Configuration and JTAG Pin I/O Requirements" on page 8–5.

☞ In a multi-device AP configuration, the board trace length between the parallel flash and the master device must follow the recommendations listed in Table 8–11.

Figure 8–11 shows the recommended balanced star routing for multiple bus master interfaces to minimize signal integrity issues.

Figure 8–11. Balanced Star Routing



Notes to Figure 8–11:

(1) Altera recommends that *M* does not exceed 6 inches, as listed in Table 8–11 on page 8–28.

(2) Altera recommends using a balanced star routing. Keep the *N* length equal and as short as possible to minimize reflection noise from the transmission line. The *M* length is applicable for this setup.

Estimating AP Configuration Time

AP configuration time is dominated by the time it takes to transfer data from the parallel flash to Cyclone IV E devices. This parallel interface is clocked by the Cyclone IV E `DCLK` output (generated from an internal oscillator). The `DCLK` minimum frequency when using the 40-MHz oscillator is 20 MHz (50 ns). In word-wide cascade programming, the `DATA[15..0]` bus transfers a 16-bit word and essentially cuts configuration time to approximately 1/16 of the AS configuration time. Equation 8–4 and Equation 8–5 show the configuration time calculations.

Equation 8–4.

$$\text{Size} \times \left(\frac{\text{maximum DCLK period}}{\text{16 bits per DCLK cycle}} \right) = \text{estimated maximum configuration time}$$

Equation 8–5.

$$9{,}600{,}000 \text{ bits} \times \left(\frac{50 \text{ ns}}{16 \text{ bit}} \right) = 30 \text{ ms}$$

The **.rbf** used by the JRunner software driver cannot be a compressed **.rbf** because the JRunner software driver uses JTAG-based configuration. During JTAG-based configuration, the real-time decompression feature is not available.

For more information about the JRunner software driver, refer to *AN 414: JRunner Software Driver: An Embedded Solution for PLD JTAG Configuration* and the source files on the Altera website at (www.altera.com).

Combining JTAG and AS Configuration Schemes

You can combine the AS configuration scheme with the JTAG-based configuration (Figure 8–28). This setup uses two 10-pin download cable headers on the board. One download cable is used in JTAG mode to configure the Cyclone IV device directly through the JTAG interface. The other download cable is used in AS mode to program the serial configuration device in-system through the AS programming interface. If you try configuring the device using both schemes simultaneously, JTAG configuration takes precedence and AS configuration terminates.

Table 8–21 lists the optional configuration pins. If you do not enable these optional configuration pins in the Quartus II software, they are available as general-purpose user I/O pins. Therefore, during configuration, these pins function as user I/O pins and are tri-stated with weak pull-up resistors.

Table 8–21. Optional Configuration Pins

Pin Name	User Mode	Pin Type	Description
CLKUSR	N/A if option is on. I/O if option is off.	Input	Optional user-supplied clock input synchronizes the initialization of one or more devices. This pin is enabled by turning on the **Enable user-supplied start-up clock (CLKUSR)** option in the Quartus II software. In AS configuration for Cyclone IV GX devices, you can use this pin as an external clock source to generate the DCLK by changing the clock source option in the Quartus II software in the **Configuration** tab of the **Device and Pin Options** dialog box.
INIT_DONE	N/A if option is on. I/O if option is off.	Output open-drain	Status pin is used to indicate when the device has initialized and is in user-mode. When nCONFIG is low, the INIT_DONE pin is tri-stated and pulled high due to an external 10-kΩ pull-up resistor during the beginning of configuration. After the option bit to enable INIT_DONE is programmed into the device (during the first frame of configuration data), the INIT_DONE pin goes low. When initialization is complete, the INIT_DONE pin is released and pulled high and the device enters user mode. Thus, the monitoring circuitry must be able to detect a low-to-high transition. This pin is enabled by turning on the **Enable INIT_DONE output** option in the Quartus II software. The functionality of this pin changes if the **Enable OCT_DONE** option is enabled in the Quartus II software. This option controls whether the INIT_DONE signal is gated by the OCT_DONE signal, which indicates the power-up on-chip termination (OCT) calibration is complete. If this option is turned off, the INIT_DONE signal is not gated by the OCT_DONE signal.
DEV_OE	N/A if option is on. I/O if option is off.	Input	Optional pin that allows you to override all tri-states on the device. When this pin is driven low, all I/O pins are tri-stated; when this pin is driven high, all I/O pins behave as programmed. This pin is enabled by turning on the **Enable device-wide output enable (DEV_OE)** option in the Quartus II software.
DEV_CLRn	N/A if option is on. I/O if option is off.	Input	Optional pin that allows you to override all clears on all device registers. When this pin is driven low, all registers are cleared; when this pin is driven high, all registers behave as programmed. You can enable this pin by turning on the **Enable device-wide reset (DEV_CLRn)** option in the Quartus II software.

Figure 8–34 shows the control register bit positions. Table 8–23 defines the control register bit contents. The numbers in Figure 8–34 show the bit position of a setting in a register. For example, bit number 35 is the enable bit for the watchdog timer.

Figure 8–34. Remote System Upgrade Control Register

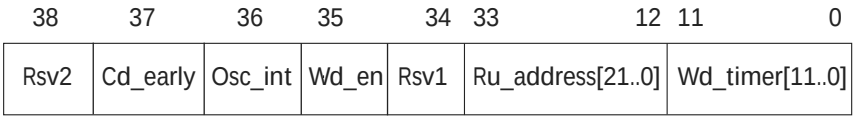


Table 8–23. Remote System Upgrade Control Register Contents

Control Register Bit	Value	Definition
Wd_timer[11..0]	12'b000000000000	User watchdog time-out value (most significant 12 bits of 29-bit count value: {Wd_timer[11..0],17'b1000})
Ru_address[21..0]	22'b0000000000000000000000	Configuration address (most significant 22 bits of 24-bit boot address value: boot_address[23:0] = {Ru_address[21..0],2'b0})
Rsv1	1'b0	Reserved bit
Wd_en	1'b1	User watchdog timer enable bit
Osc_int (1)	1'b1	Internal oscillator as startup state machine clock enable bit
Cd_early (1)	1'b1	Early CONF_DONE check
Rsv2	1'b1	Reserved bit

Note to Table 8–23:

(1) Option bit for the application configuration.

When enabled, the early CONF_DONE check (Cd_early) option bit ensures that there is a valid configuration at the boot address specified by the factory configuration and that it is of the proper size. If an invalid configuration is detected or the CONF_DONE pin is asserted too early, the device resets and then reconfigures the factory configuration image. The internal oscillator (as the startup state machine clock [Osc_int] option bit) ensures a functional startup clock to eliminate the hanging of startup. When all option bits are turned on, they provide complete coverage for the programming and startup portions of the application configuration. Altera recommends turning on both the Cd_early and Osc_int option bits.

☞ The Cd_early and Osc_int option bits for the application configuration must be turned on by the factory configuration.

Remote System Upgrade Status Register

The remote system upgrade status register specifies the reconfiguration trigger condition. The various trigger and error conditions include:

- Cyclical redundancy check (CRC) error during application configuration
- nSTATUS assertion by an external device due to an error
- Cyclone IV device logic array triggers a reconfiguration cycle, possibly after downloading a new application configuration image

Table 9–7 lists the input and output ports that you must include in the atom.

Table 9–7. CRC Block Input and Output Ports

Port	Input/Output	Definition
<crcblock_name>	Input	Unique identifier for the CRC block, and represents any identifier name that is legal for the given description language (for example, Verilog HDL, VHDL, and AHDL). This field is required.
.clk(*<clock source>*	Input	This signal designates the clock input of this cell. All operations of this cell are with respect to the rising edge of the clock. Whether it is the loading of the data into the cell or data out of the cell, it always occurs on the rising edge. This port is required.
.shiftnld (*<shiftnld source>*)	Input	This signal is an input into the error detection block. If `shiftnld=1`, the data is shifted from the internal shift register to the `regout` at each rising edge of `clk`. If `shiftnld=0`, the shift register parallel loads either the pre-calculated CRC value or the update register contents, depending on the `ldsrc` port input. To do this, the `shiftnld` must be driven low for at least two clock cycles. This port is required.
.ldsrc (*<ldsrc source>*)	Input	This signal is an input into the error detection block. If `ldsrc=0`, the pre-computed CRC register is selected for loading into the 32-bit shift register at the rising edge of `clk` when `shiftnld=0`. If `ldsrc=1`, the signature register (result of the CRC calculation) is selected for loading into the shift register at the rising edge of `clk` when `shiftnld=0`. This port is ignored when `shiftnld=1`. This port is required.
.crcerror (*<crcerror indicator output>*)	Output	This signal is the output of the cell that is synchronized to the internal oscillator of the device (80-MHz internal oscillator) and not to the `clk` port. It asserts high if the error block detects that a SRAM bit has flipped and the internal CRC computation has shown a difference with respect to the pre-computed value. You must connect this signal either to an output pin or a bidirectional pin. If it is connected to an output pin, you can only monitor the CRC_ERROR pin (the core cannot access this output). If the CRC_ERROR signal is used by core logic to read error detection logic, you must connect this signal to a `BIDIR` pin. The signal is fed to the core indirectly by feeding a `BIDIR` pin that has its output enable port connected to V_{CC} (see Figure 9–3 on page 9–8).
.regout (*<registered output>*)	Output	This signal is the output of the error detection shift register synchronized to the `clk` port to be read by core logic. It shifts one bit at each cycle, so you should clock the `clk` signal 31 cycles to read out the 32 bits of the shift register.

Recovering from CRC Errors

The system that the Altera FPGA resides in must control device reconfiguration. After detecting an error on the CRC_ERROR pin, strobing the nCONFIG low directs the system to perform the reconfiguration at a time when it is safe for the system to reconfigure the FPGA.

When the data bit is rewritten with the correct value by reconfiguring the device, the device functions correctly.

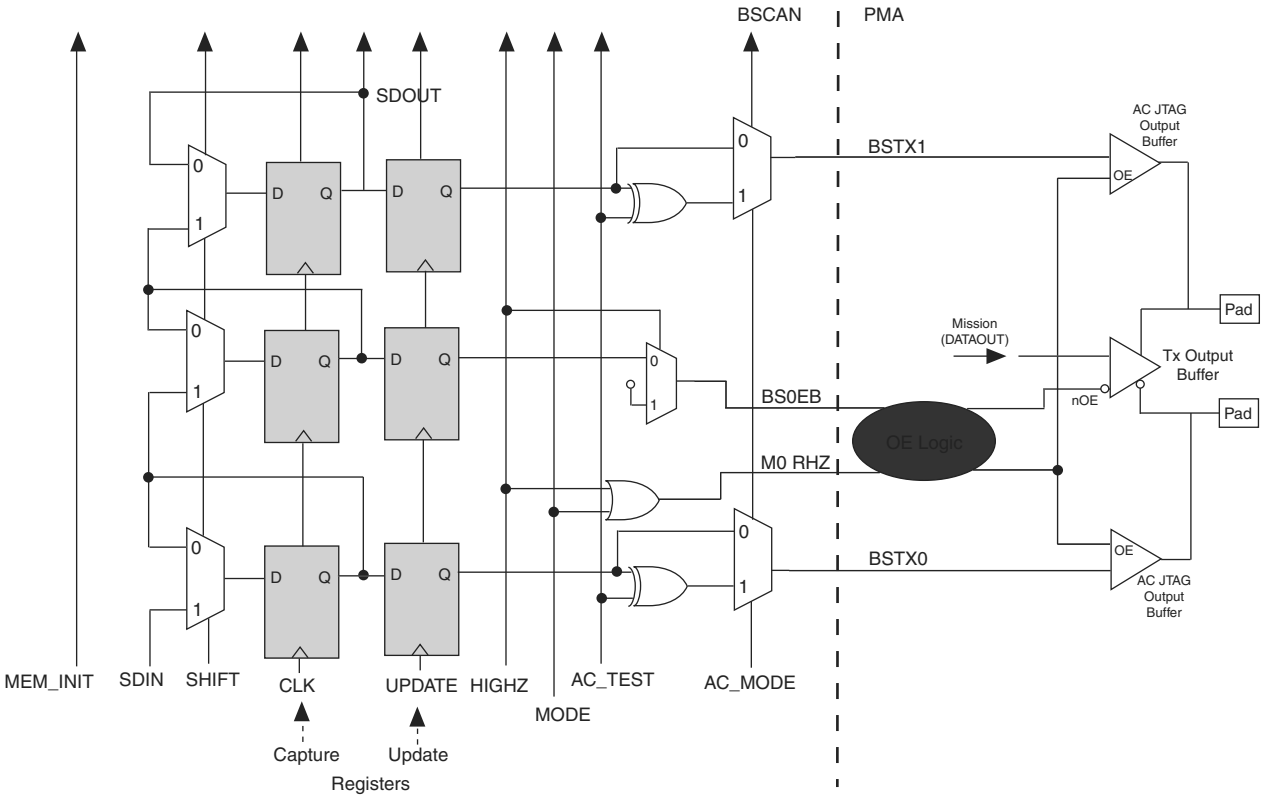
While soft errors are uncommon in Altera devices, certain high-reliability applications might require a design to account for these errors.

IEEE Std. 1149.6 Boundary-Scan Register

The boundary-scan cell (BSC) for HSSI transmitters (GXB_TX[p,n]) and receivers (GXB_RX[p,n]) in Cyclone IV GX devices are different from the BSCs for I/O pins.

Figure 10–1 shows the Cyclone IV GX HSSI transmitter boundary-scan cell.

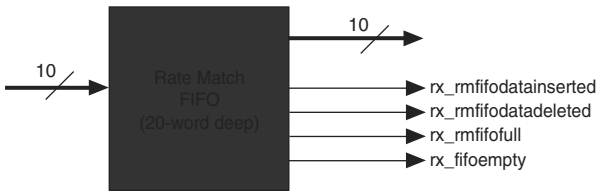
Figure 10–1. HSSI Transmitter BSC with IEEE Std. 1149.6 BST Circuitry for Cyclone IV GX Devices



Rate Match FIFO

In asynchronous systems, the upstream transmitter and local receiver can be clocked with independent reference clocks. Frequency differences in the order of a few hundred ppm can corrupt the data when latching from the recovered clock domain (the same clock domain as the upstream transmitter reference clock) to the local receiver reference clock domain. Figure 1–21 shows the rate match FIFO block diagram.

Figure 1–21. Rate Match FIFO Block Diagram



The rate match FIFO compensates for small clock frequency differences of up to ±300 ppm (600 ppm total) between the upstream transmitter and the local receiver clocks by performing the following functions:

- Insert skip symbols when the local receiver reference clock frequency is greater than the upstream transmitter reference clock frequency
- Delete skip symbols when the local receiver reference clock frequency is less than the upstream transmitter reference clock frequency

The 20-word deep rate match FIFO and logics control insertion and deletion of skip symbols, depending on the ppm difference. The operation begins after the word aligner synchronization status (`rx_syncstatus`) is asserted.

Rate match FIFO is only supported with 8B/10B encoded data and the word aligner in automatic synchronization state machine mode.

8B/10B Decoder

The 8B/10B decoder receives 10-bit data and decodes it into an 8-bit data and a 1-bit control identifier. The decoder is compliant with Clause 36 of the IEEE 802.3 specification.

Figure 1–22 shows the 8B/10B decoder block diagram.

Figure 1–22. 8B/10B Decoder Block Diagram

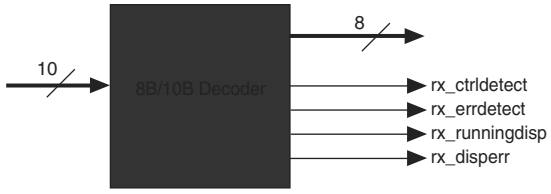


Table 1–9 lists the high- and low-speed clock sources for each channel.

Table 1–9. High- and Low-Speed Clock Sources for Each Channel in Non-Bonded Channel Configuration

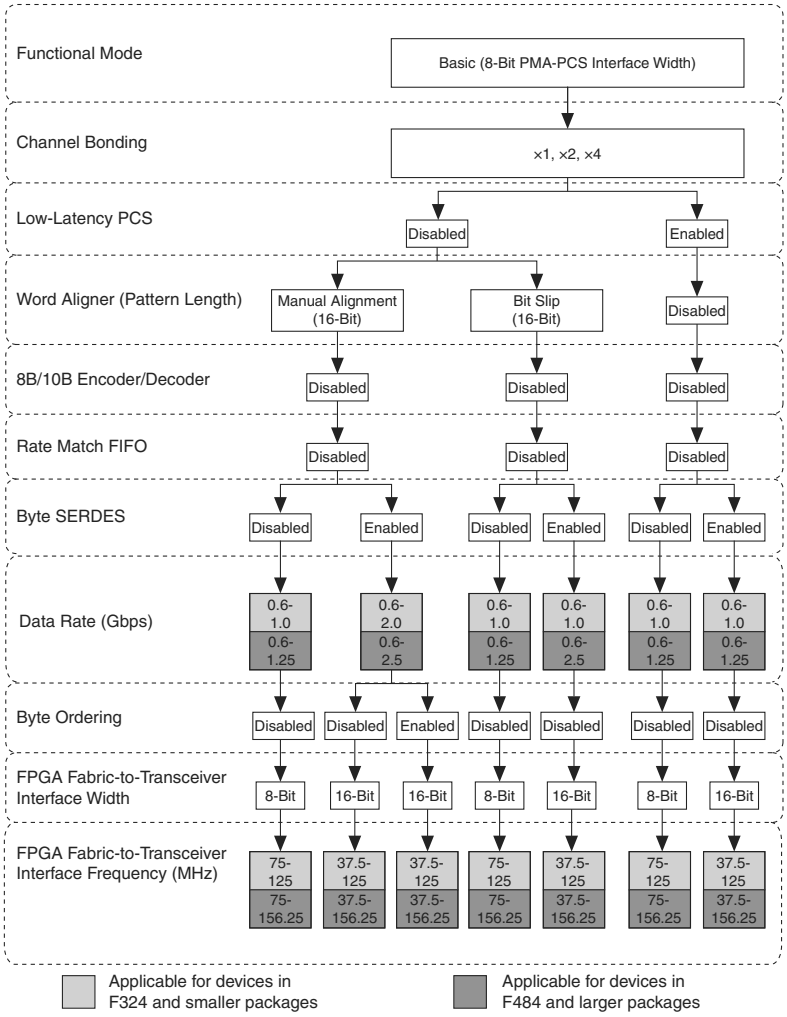
Package	Transceiver Block	Transceiver Channel	High- and Low-Speed Clocks Sources	
			Option 1	Option 2
F324 and smaller	GXBL0	All channels	MPLL_1	MPLL_2
F484 and larger	GXBL0	Channels 0, 1	MPLL_5/GPLL_1	MPLL_6
		Channels 2, 3	MPLL_5	MPLL_6/MPLL_7 (1)
	GXBL1 (1)	Channels 0, 1	MPLL_7/MPLL_6	MPLL_8
		Channels 2, 3	MPLL_7	MPLL_8/GPLL_2

Note to Table 1–9:

(1) MPLL_7 and GXBL1 are not applicable for transceivers in F484 package

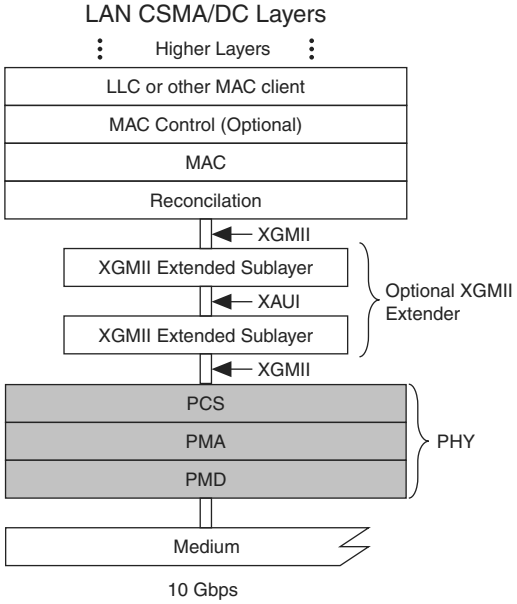
Figure 1–45 and Figure 1–46 show the supported transceiver configurations in Basic mode with the 8-bit and 10-bit PMA-PCS interface width respectively.

Figure 1–45. Supported Transceiver Configurations in Basic Mode with the 8-bit PMA-PCS Interface Width



converted within the XGMII extender sublayer into an 8B/10B encoded data stream. Each data stream is then transmitted across a single differential pair running at 3.125 Gbps. At the XAUI receiver, the incoming data is decoded and mapped back to the 32-bit XGMII format. This provides a transparent extension of the physical reach of the XGMII and also reduces the interface pin count.

Figure 1–62. XAUI in 10 Gbps LAN Layers



XAUI functions as a self-managed interface because code group synchronization, channel deskew, and clock domain decoupling is handled with no upper layer support requirements. This functionality is based on the PCS code groups that are used during the inter-packet gap time and idle periods.

Table 1–7. Bus Hold Parameter for Cyclone IV Devices (Part 2 of 2) (1)

Parameter	Condition	V_{CCIO} (V)												Unit
		1.2		1.5		1.8		2.5		3.0		3.3		
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Bus hold trip point	—	0.3	0.9	0.375	1.125	0.68	1.07	0.7	1.7	0.8	2	0.8	2	V

Note to Table 1–7:

(1) Bus hold trip points are based on the calculated input voltages from the JEDEC standard.

OCT Specifications

Table 1–8 lists the variation of OCT without calibration across process, temperature, and voltage (PVT).

Table 1–8. Series OCT Without Calibration Specifications for Cyclone IV Devices

Description	V_{CCIO} (V)	Resistance Tolerance		Unit
		Commercial Maximum	Industrial, Extended industrial, and Automotive Maximum	
Series OCT without calibration	3.0	±30	±40	%
	2.5	±30	±40	%
	1.8	±40	±50	%
	1.5	±50	±50	%
	1.2	±50	±50	%

OCT calibration is automatically performed at device power-up for OCT-enabled I/Os.

Table 1–9 lists the OCT calibration accuracy at device power-up.

Table 1–9. Series OCT with Calibration at Device Power-Up Specifications for Cyclone IV Devices (1)

Description	V_{CCIO} (V)	Calibration Accuracy		Unit
		Commercial Maximum	Industrial, Extended industrial, and Automotive Maximum	
Series OCT with calibration at device power-up	3.0	±10	±10	%
	2.5	±10	±10	%
	1.8	±10	±10	%
	1.5	±10	±10	%
	1.2	±10	±10	%

Note to Table 1–9:

(1) This specification is not applicable to EP4CGX15, EP4CGX22, and EP4CGX30 devices.